

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L95	1	"20020180449"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:36
L94	1642	700/121.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:36
L92	8180	L89 and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:36
L91	0	(semiconductor with tool) and (empirical with model)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:36
L17	3	(CFRDC) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:36
L93	805	703/22.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L90	1444	L89 and geometric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L89	19972	(data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L88	740	(ELIEN) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L87	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L86	1	(tool) and (empirical with model)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L85	3	(CFRDC) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L84	3	L49 and (converg\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L83	2	L54 and (adjust\$6).cm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L82	4	L81 and Geometric\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L81	19	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016594-\$).id. or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628899-\$ or US-643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$).id. or (US-5866437-\$ or US-20030135302-\$ or US-20040078319-\$ or US-20050010319-\$).id.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L80	0	(semiconductor and tool) and (empirical with model) (ANSYS) with simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L79	127		US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L78	0	(processing with tool) and (empirical with model)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L77	1	L54 and (nonlinear\$3 multivariate).	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L76	5	L75 and empirical	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L75	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L74	5	L54 and control\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L73	9	L49 and (adjust)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L72	1	L49 and (calibration)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34
L71	2	L70 and (rate).cm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	OFF	2006/09/19 11:34

EAST Search History

L70	5	"10/673501" "10/673583" "10/673138" "10/673467" L68 and rate	US-PGPUB; OR US-PGPUB; OR US-PGPUB; OR US-PGPUB; OR US-PGPUB; OR	OFF OFF OFF OFF OFF	2006/09/19 11:34 2006/09/19 11:34 2006/09/19 11:34 2006/09/19 11:34 2006/09/19 11:34
L69	8	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628809-\$ or US-6643616-\$ or US-6728591-\$ or US-677645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$); did or US-20030135302-\$ or US-20040078319-\$ or US-2005010319-\$; did	US-PGPUB; OR US-PGPUB; OR US-PGPUB; OR US-PGPUB; OR US-PGPUB; OR	OFF OFF OFF OFF OFF	2006/09/19 11:34 2006/09/19 11:34 2006/09/19 11:34 2006/09/19 11:34 2006/09/19 11:34
L68	19	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628809-\$ or US-6643616-\$ or US-6728591-\$ or US-677645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$); did or US-20030135302-\$ or US-20040078319-\$ or US-2005010319-\$; did	US-PGPUB; OR US-PGPUB; OR US-PGPUB; OR US-PGPUB; OR US-PGPUB; OR	OFF OFF OFF OFF OFF	2006/09/19 11:34 2006/09/19 11:34 2006/09/19 11:34 2006/09/19 11:34 2006/09/19 11:34
L67	3	L54 and (control56).c1m.	US-PGPUB; OR	OFF	2006/09/19 11:34
L66	3	L49 and (nonlinear3 multivariate)	US-PGPUB; OR	OFF	2006/09/19 11:34
L65	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB; OR	OFF	2006/09/19 11:34
L64	215	(FLUENT) with simulat4	US-PGPUB; OR USOCR; EPO; JPO; DERWENT; IBM_TDB	ON	2006/09/19 11:34
L63	50	("5340697" "5374327" "5382823" "5384289" "5400435" "5406309" "5409547" "5418337" "54227716" "542644" "5435928" "5459020" "54409547" "5453894" "5463093" "5474884" "5478702" "5490953" "5493501" "5495417" "5511005" "5517140" "5523022" "55358964" "5561612" "5571662" "55933608" "5596695" "5617322" "5619159" "5629877" "5637151" "56560947" "5654904" "5658706" "5663889" "5672468" "5672907" "5684723" "5694325" "5694052" "56959364" "5705200" "5709757" "5712794" "5714678" "5715170" "5725974" "5728514" "5731636" "5736024" "5737242" "57453587");.pn.	US-PGPUB; OR	OFF	2006/09/19 11:34

EAST Search History

L62	4	(US-20050016947-\$); did or (US-6625497-\$ or US-5629877-\$ or US-5377116-\$ or US-5719796-\$ or US-6802045-\$ or US-6812045-\$); did.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L61	5	"10/673501" "10/673583" "10/673138" "10/673467"	US-PGPUB; OR	OR	OFF	2006/09/19 11:34
L60	3	(input with size) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L59	5	(geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing)) geometric and (data parameter) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L58	87	geometric with (data parameter) with (etch deposition coating lithography (thermal adj annealing)) (ANSYS) and simulat4	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L57	29	geometric with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L56	297	(ANSYS) and simulat4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L55	50	("5386906" "5386363" "6031246" "56049651" "56095161" "56268951" "56282253" "5604774" "5446742" "56300491" "56168891" "56178544" "56207630" "5343878" "44435322" "4481049" "4491530" "4500798" "45330587" "4564921" "5581706" "4582683" "4597985" "4602153" "4615782" "4769817" "792883" "4801713" "4822716" "4845986" "4873561" "4952666" "4969748" "4984902" "4989166" "4999282" "5006717" "5017453" "5059516" "5198520" "5215956" "5243528" "5248956" "5288604" "5312723" "5312724" "5330884" "5331420" "5336752" "5339393");.pn.	OR	OFF	2006/09/19 11:34	
L54	5	"10/673501" "10/673583" "10/673138" "10/673467"	US-PGPUB	OR	OFF	2006/09/19 11:34

EAST Search History

L53	163	(FLUENT) and simulat\$4 and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L52	6	(empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L51	2	(physical with geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L50	0	semiconductor with tool with empirical with model	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L49	19	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016947-\$) did, or (US-571936-\$ or US-6571371-\$ or US-6615097-\$ or US-66238809-\$ or US-6643616-\$ or US-6728891-\$ or US-6757645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-69058935-\$). did, or (US-586437-\$ or WO-200177979-\$ or WO-2002775389-\$ or US-200301353102-\$ or US-20040078319-\$ or US-20050010319-\$) did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L48	5433	(ANSYS FLUENT CFDRC (Monte adj Carlo)) and simulat\$4	US-PGPUB; USPAT	OR	ON	2006/09/19 11:34
L47	6	(empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L46	1	(tool) and (empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L45	0	(semiconductor and tool) and (empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L44	0	(processing with tool) and (empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L43	0	(semiconductor with tool) and (empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L42	0	semiconductor with tool with empirical with model	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34

EAST Search History

L41	5	L40 and empirical	US-PGPUB	OR	OFF	2006/09/19 11:34
L40	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L39	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L38	805	703/22.ods.	US-PGPUB;	USPAT	OFF	2006/09/19 11:34
L37	4	(US-2005016947-\$).did. or US-5629877-\$ or US-5377116-\$ or US-5719796-\$ or US-6802045-\$ or US-6812045-\$). did.	US-PGPUB;	USPAT	OFF	2006/09/19 11:34
L36	50	("3406597" "5274427" "5382823" "5406589" "5406435" "5406309" "5409547" "5413937" "5427716" "542644" "5455928" "5459020" "5474884" "5478702" "5490953" "5499501" "5499417" "5511005" "5511740" "5522022" "5538964" "5561612" "5571662" "5593608" "5596695" "5617322" "5619159" "5629877" "5637151" "5650947" "5654994" "5658706" "5663889" "5672468" "5677907" "5684723" "5694325" "5694052" "5692664" "5706200" "5707957" "5712794" "5714678" "5715170" "5725974" "5728514" "5731626" "5736024" "573742" "5745388").pn.	USPAT	OR	OFF	2006/09/19 11:34
L35	50	("5886906" "5886363" "6031246" "5044966" "5095161" "52658951" "54782253" "5004774" "5446742" "56030491" "6168891" "6178544" "6207630" "6348878" "4435322" "4481049" "4491536" "4500798" "4530587" "4564921" "4581706" "4582683" "4597985" "4602153" "4615782" "4769817" "4792883" "4801713" "4822716" "4842986" "4873661" "4952666" "4969748" "4984902" "4989166" "4999282" "5006717" "5017453" "5039516" "5198520" "5213996" "5243538" "5248956" "5288604" "5312723" "5312724" "5330884" "5331420" "5336752" "5339039").pn.	USPAT	OR	OFF	2006/09/19 11:34
L34	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34

EAST Search History

L33	3	(input with size) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L32	5	(geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L31	2	(physical with geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L30	87	geometric and (data parameter) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L29	29	geometric with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L28	1444	L26 and geometric	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L27	8180	L26 and (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L26	19972	(data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L25	4	L24 and Geometries\$4	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L24	19	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-2005016947-\$), did, or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6623809-\$ or US-6643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$), did, or (US-5866437-\$ or US-20030133302-\$ or US-20040078319-\$ or US-2005010319-\$), did,	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L23	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34

EAST Search History

L22	163	(FLUENT) and simulat\$4 and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; IPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L21	127	(ANSYS) with simulat\$4	US-PGPUB; USPAT; USOCR; EPO; IPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L20	215	(FLUENT) with simulat\$4	US-PGPUB; USPAT; USOCR; EPO; IPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L19	1642	700/121.cds,	US-PGPUB; USPAT; USOCR; EPO; IPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L18	740	(FLUENT) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; IPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L16	297	(ANSYS) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; IPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L15	5433	(ANSYS FLUENT CFRDC (Monte adj Caro)) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; IPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34
L14	3	L3 and (converg\$5)	US-PGPUB; USPAT; USOCR; EPO; IPO; DERVENT; IBM_TDB	OR	ON	2006/09/19 11:34

EAST Search History

EAST Search History

L1	L2	L3	9	L3 and (adjust)	US-PPGPUB; OR	ON	2006/09/19 11:34
L3	1	L3 and (calibration)		US-PPGPUB; OR	OFF	2006/09/19 11:34	
L2	1	L3 and (nonlinear\$3 multivariate)		US-PPGPUB; OR	OFF	2006/09/19 11:34	
L1	3	L6 and (nonlinear\$3 multivariate)		US-PPGPUB; OR	OFF	2006/09/19 11:34	
L10	1	L6 and (nonlinear\$3 multivariate).dim.		US-PPGPUB; OR	OFF	2006/09/19 11:34	
L9	2	L6 and (adjust\$6).clm.		US-PPGPUB; OR	OFF	2006/09/19 11:34	
L8	3	L6 and (control\$6).clm.		US-PPGPUB; OR	OFF	2006/09/19 11:34	
L7	5	L6 and control\$6		US-PPGPUB; OR	OFF	2006/09/19 11:34	
L6	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"		US-PPGPUB; OR	OFF	2006/09/19 11:34	
L5	8	L4 and rate		US-PPGPUB; USPAT	OFF	2006/09/19 11:34	
L4	19	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016947-\$).did. or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628809-\$ or US-6643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$). did. or (US-5866437-\$ or US-20030135302-\$ or US-20040078319-\$ or US-20050010319-\$).did.		US-PPGPUB; USPAT	OFF	2006/09/19 11:34	
L3	19	(US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016947-\$).did. or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628809-\$ or US-6643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774998-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$). did. or (US-5866437-\$ or WO-200177979-\$ or WO-200277589-\$ or US-20030135302-\$ or US-20040078319-\$ or US-20050010319-\$).did.		US-PPGPUB; USPAT	OFF	2006/09/19 11:34	
L2	2	L1 and (rate).clm.		US-PPGPUB	OFF	2006/09/19 11:34	

EAST Search History

EAST Search History

L1	L2	L3	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PPGPUB	OR	OFF	2006/09/19 11:34